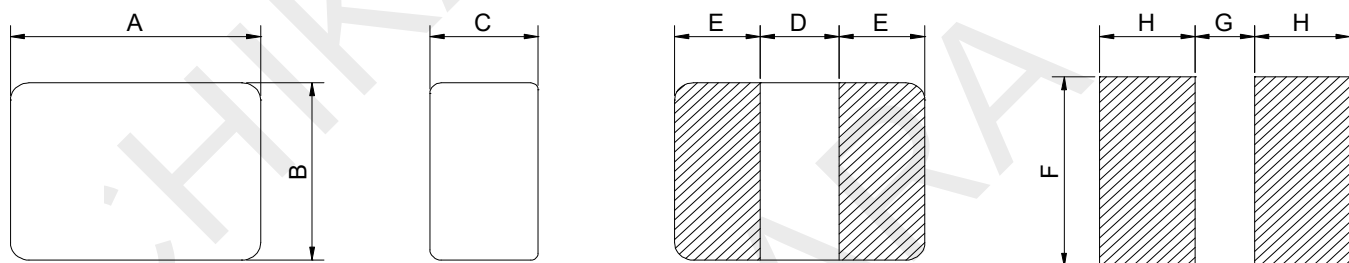


Features

- Compact design, Flat wire
- Storage temperature range:-55°C to + 125°C
- Operating temperature range:-55°C to + 125°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:3000pcs. Per 7-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



Recommended Layout

A	B	C	D	E	F	G	H
2.0±0.2	1.6±0.2	0.9Max.	0.6±0.2	0.7±0.2	1.8	0.5	0.85

Part Number Description

SP16 - 201608 R22 M

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic

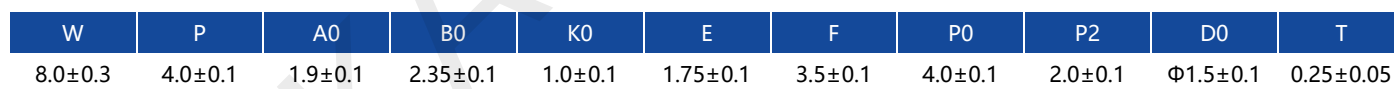


Electrical Characteristic

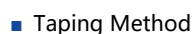
Part Number	Inductance L0(uH)	DCR		Isat		Irms	
		(mΩ)Max.	(mΩ)Typ.	(A)Max.	(A)Typ.	(A)Max.	(A)Typ.
SP16-201608R22M	0.22±20%	19	14	5.6	6.1	5.9	6.6
SP16-201608R24M	0.24±20%	20	14	5.5	6.0	5.8	6.5
SP16-201608R33M	0.33±20%	24	18	5.3	5.8	4.8	5.5
SP16-201608R47M	0.47±20%	27	24	5.0	5.5	4.4	4.6
SP16-201608R68M	0.68±20%	44	39	4.2	4.6	3.5	3.8
SP16-2016081R0M	1.0±20%	60	53	3.1	3.3	3.3	3.6
SP16-2016081R5M	1.5±20%	85	73	2.8	3.0	2.8	3.1
SP16-2016082R2M	2.2±20%	140	123	2.3	2.5	2.0	2.2
SP16-2016083R3M	3.3±20%	220	200	1.8	2.1	1.5	1.8
SP16-2016084R7M	4.7±20%	290	260	1.5	1.7	1.4	1.6

- Test frequency and voltage:1MHz,1Vrms.
- All test data referenced to 25°C ambient.
- Absolute maximum voltage: 20Vdc.
- Saturation current(Isat) will cause L0 to drop approximately 30%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It' s suggested to verify the temperature rise of the component under the real operation application conditions.

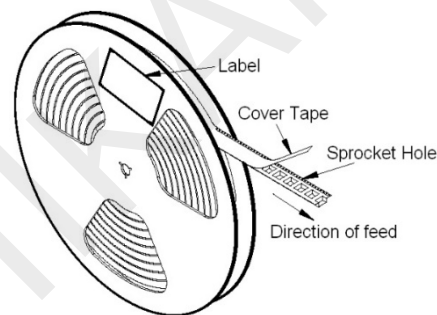
- Carrier Tape (Unit:mm)



A	B	C	D
$\Phi 178 \pm 2.0$	11.5Max.	$\Phi 50 \text{Min.}$	9.0 ± 0.5



Peel-off strength	Peel-off angle	Peel-off speed
F=0.1N~1.0N	165°~180°	300mm/min.



✖ Packing is referred to the international standard IEC 60286-3.

Parts per reel

3000Pcs

Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (Tp)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.